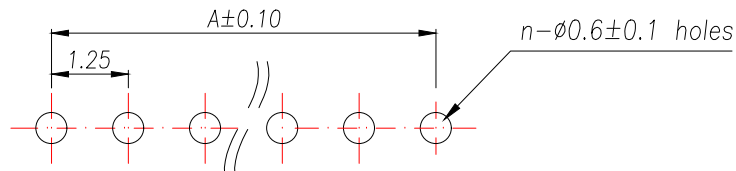
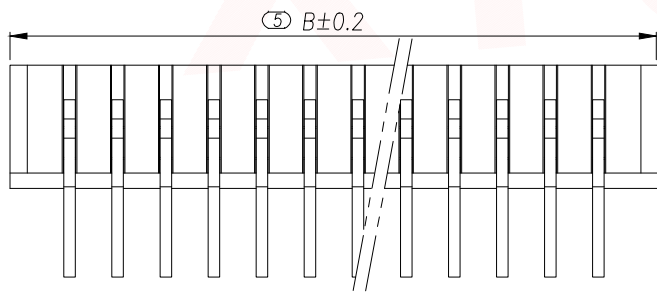
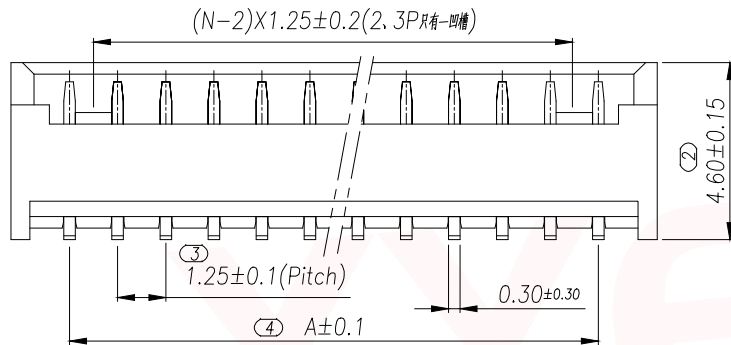
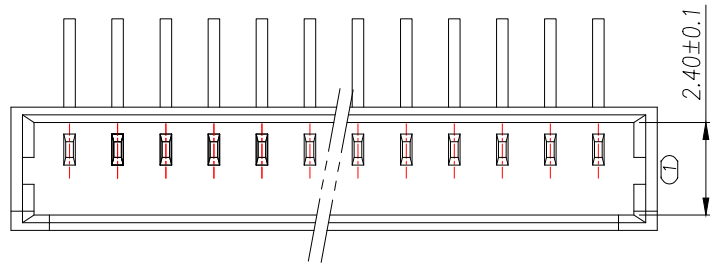
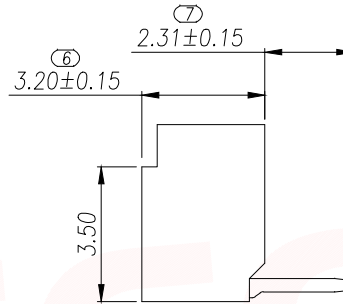


REV.	Q'TY	ECN. NO.	APR.	DATE



PCB寸法  
PCB Layout



技术指标:

- 1、塑件表面应光洁、无毛刺、明显收缩、缺陷、裂纹等现象;
- 2、温度范围: -25°C~85°C;
- 3、额定电压: 200V, AC, DC(等效);
- 4、额定电流: 1A
- 5、接触电阻: <math>\leq 0.03\Omega</math>;
- 6、绝缘电阻: <math>\geq 1000M\Omega</math>;
- 7、耐压: 1000V, AC/minute.

PRELIMINARY  
DESIGN IS SUBJECT  
TO CHANGE WITHOUT  
PRIOR NOTICE

ROHS管理规定:

- 1、禁止使用含有ROHS指令所限制的物质。
- 2、对应的SGS或ITS出具的ICP-AES数据, 不可测定物质的成分表, 有效期一年。

Part No	PIN	A	B
XY-MX1.25-2A21	2	1.25	4.3
XY-MX1.25-3A21	3	2.5	5.55
XY-MX1.25-4A21	4	3.75	6.8
XY-MX1.25-5A21	5	5	8.05
XY-MX1.25-6A21	6	6.25	9.3
XY-MX1.25-7A21	7	7.5	10.55
XY-MX1.25-8A21	8	8.75	11.8
XY-MX1.25-9A21	9	10	13.05
XY-MX1.25-10A21	10	11.25	14.3
XY-MX1.25-11A21	11	12.5	15.55
XY-MX1.25-12A21	12	13.75	16.8
XY-MX1.25-13A21	13	15	18.05
XY-MX1.25-14A21	14	16.25	19.3
XY-MX1.25-15A21	15	17.5	20.55
XY-MX1.25-16A21	16	18.75	21.8

2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN,再镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	本色
序号	名称	材料	数量	备注

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyconn Electronics Co.,Ltd		
TOLERANCE UNLESS OTHERWISE SPECIFIED				
.X±0.35	X.*±5°	APR.	Alex	TITLE: WAFER 1.25mm H4.9mm 180°SMT
.XX±0.25	.X.*±3°	CHK.	Jack	DWG NO. XY-MX1.25-NA21
.XXX±0.15	.XX.*±1°	DRA.	Can	PROJ.  CUSTOMER DRAWING
SIZE A4	SCALE 1:1	SHEET 1/1	REV. A	